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December 2013

## FCPF7N60NT

## N-Channel MOSFET 600 V, 6.8 A, 0.52 $\Omega$

#### **Features**

- Typ  $R_{DS(on)} = 460 m\Omega$
- Ultra Low Gate Charge (typ.  $Q_g$  = 17.8 nC)
- Low Effective Output Capacitance (typ.  $C_{oss(eff.)} = 91 pF$ )
- 100% Avalanche Tested
- · RoHS Compliant

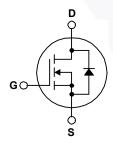
### **Application**

- · Solar Inverter
- AC-DC Power Supply



## Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.



#### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter	FCPF7N60NT	Units
V <sub>DSS</sub>	Drain to Source Voltage		600	V
V <sub>GSS</sub>	Gate to Source Voltage		±30	V
	Dunin Cumant	-Continuous (T <sub>C</sub> = 25°C)	6.8*	_
ID	Drain Current	-Continuous (T <sub>C</sub> = 100°C)	4.3*	A
I <sub>DM</sub>	Drain Current	- Pulsed (Note	1) 20.4	Α
E <sub>AS</sub>	Single Pulsed Avalanch	ne Energy (Note 2	2) 79.4	mJ
I <sub>AR</sub>	Avalanche Current		6.8	Α
E <sub>AR</sub>	Repetitive Avalanche E	ve Avalanche Energy		mJ
عاد ، اعا	MOSFET dv/dt Rugged	OSFET dv/dt Ruggedness		V/ns
dv/dt	Peak Diode Recovery d	lv/dt (Note:	3) 4.9	V/ns
D	Damas Diada atian	(T <sub>C</sub> = 25°C)	30.5	W
$P_{D}$	Power Dissipation	- Derate above 25°C	0.24	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage	Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temper 1/8" from Case for 5 Se	rature for Soldering Purpose, conds	300	°C

<sup>\*</sup>Drain current limited by maximum junction temperature.

#### **Thermal Characteristics**

Symbol	Parameter	FCPF7N60NT	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	4.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. 62.5		°C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCPF7N60NT	FCPF7N60NT	TO-220F	-	-	50

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 1 \text{mA}, V_{GS} = 0 \text{V}, T_C = 25^{\circ} \text{C}$	600	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1mA, Referenced to 25°C	-	0.6	-	V/°C
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480V, V <sub>GS</sub> = 0V	-	-	10	μА
I <sub>DSS</sub> Ze	Zero Gate voltage Drain Current	$V_{DS} = 480V, V_{GS} = 0V, T_{C} = 125^{\circ}C$	-	-	100	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 3.4A$	-	0.46	0.52	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20V, I_{D} = 3.4A$	-	8.5	-	S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	100// 1/	-	719	960	pF
Coss	Output Capacitance	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V f = 1MHz		30	40	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11/11/2	-	2.1	3.2	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380V, V <sub>GS</sub> = 0V, f = 1MHz	- \	17	-	pF
C <sub>oss</sub> eff	Effective Output Capacitance	$V_{DS}$ = 0V to 380V, $V_{GS}$ = 0V	-	91	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	$V_{DS} = 380V, I_{D} = 3.4A$	-	17.8	35.6	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10V	-	3.2	6.3	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	6.0	11.9	nC
ESR	Equivalent Series Resistance (G-S)	Drain Open	-	2.5	-	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		- /	12	24	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 380V, I_D = 3.4A$	-/	6	22	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 4.7\Omega$		35	80	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	7/-	12	24	ns

#### **Drain-Source Diode Characteristics**

l <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	6.8	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	20.4	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> =3.4A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 3.4A	-	211	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	1.8	-	μC

#### Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I<sub>AS</sub> = 12A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , starting T<sub>J</sub> = 25 $^{\circ}$ C.
- 3. I  $_{SD} \leq$  36A, di/dt  $\leq$  200A/µs, V  $_{DD}$  = 380V starting T  $_{J}$  = 25°C.
- 4. Essentially independent of operating temperature.

#### **Typical Characteristics**

Figure 1. On-Region Characteristics

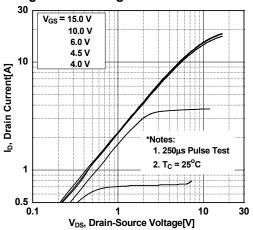


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

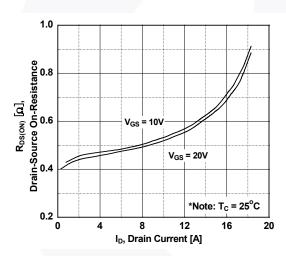


Figure 5. Capacitance Characteristics

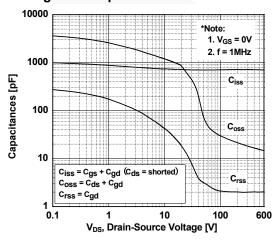


Figure 2. Transfer Characteristics

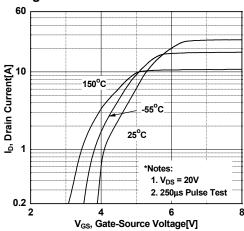


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

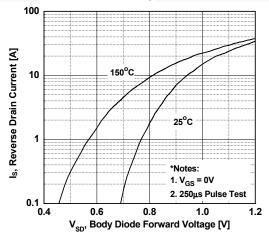
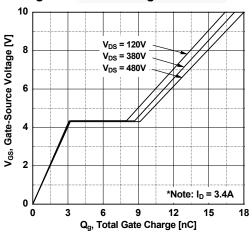


Figure 6. Gate Charge Characteristics



## **Typical Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

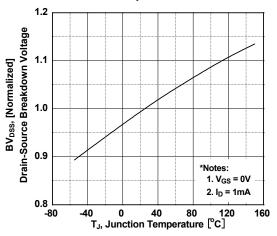


Figure 9. Maximum Safe Operating Area \_ FCPF7N60NT

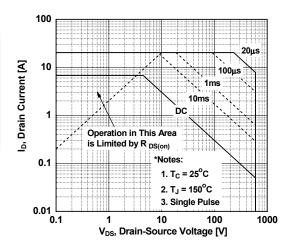


Figure 8. On-Resistance Variation vs. Temperature

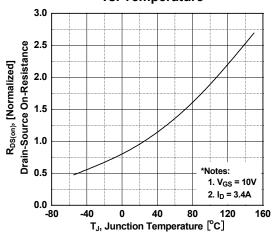
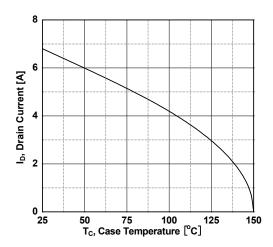


Figure 10. Maximum Drain Current vs. Case Temperature



## Typical Characteristics (Continued)

**Figure 11. Transient Thermal Response Curve** 

\_FCPF7N60NT

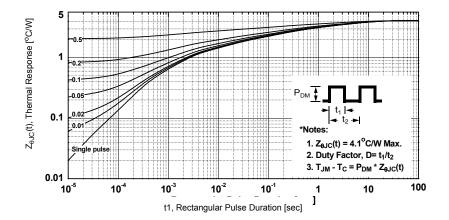


Figure 12. Gate Charge Test Circuit & Waveform

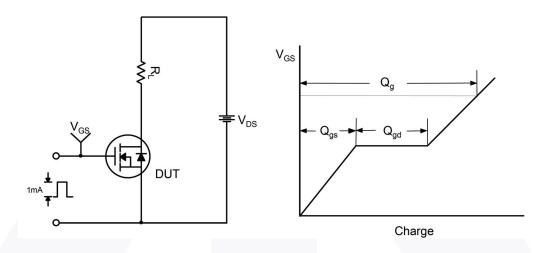


Figure 13. Resistive Switching Test Circuit & Waveforms

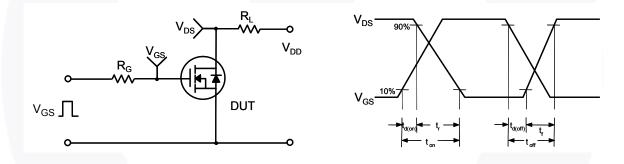
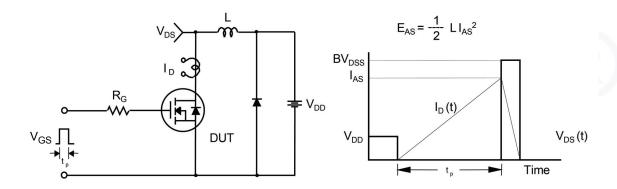


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



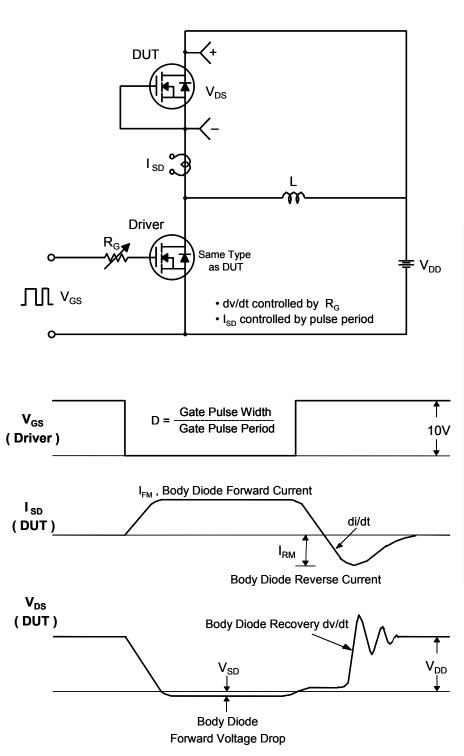


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**

## TO-220F 3L

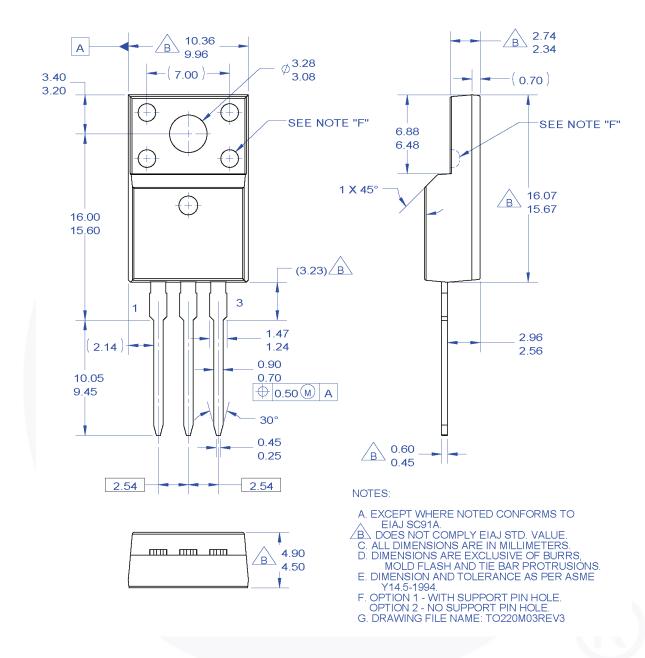


Figure 16. TO220, Molded, 3LD, Full Pack, EIAJ SC91, Straight Lead

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